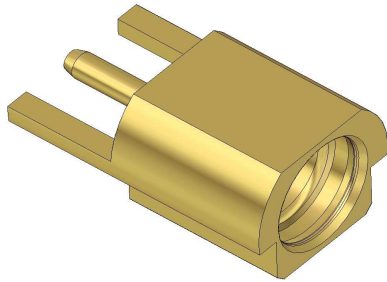


Part Number: 1683.09.2610.001		Revision: b		
Description: p.c.b. mount jack		Date: 15.01.2002		
		Signature: Schwaer		
		Page: 1 of 5		
Design according to:		CECC 22340		
Electrical characteristics:	colored value means: still under test target value			
	Value	Unit	Picture	
	Impedance (MIL-C- 39012B)	50	[Ω]	
	Operating frequency up to	6	[GHz]	
	Return loss			
	1 GHz	>35	[dB]	
	2 GHz	>32	[dB]	
	4 GHz	>28	[dB]	
	6 GHz	>21	[dB]	
				Remarks
	Insulation resistance	30	[GΩ]	
	Contact resistance			
	Centre contact	2,19	[mΩ]	
	Outer contact	0,45	[mΩ]	
	Contact current max. (DC)	1	[A]	
Operating voltage	170	[V]		
Proof voltage	1500	[V]		
Mechanical characteristics:	Value	Unit	Remarks	
	Engagement force	5 - 15	[N]	
	Separating force	6 - 15	[N]	
	Mating cycles	500	-	

Product data sheet

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D-79840 Löffingen

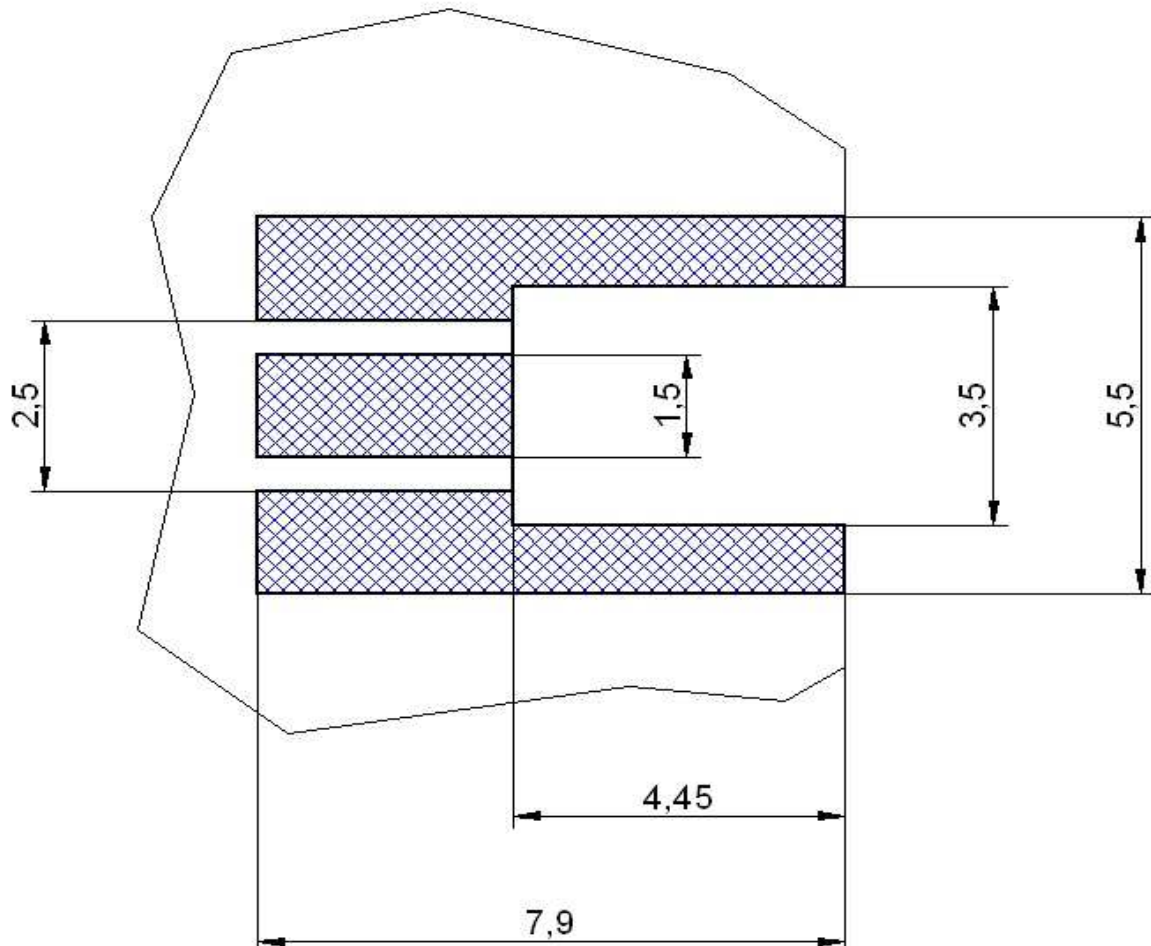
Tel (+49) 7654 901-0
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Net: www.imscs.com
E-mail: sales@imscs.com

Part Number: 1683.09.2610.001

Description: p.c.b. mount jack

Revision: b
Date: 15.01.2002
Signature: Schwaer
Page: 3 of 5

Solderpad -Layout (recommended):



Product data sheet

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Description: p.c.b. mount jack

Revision: b
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Signature: Schwaer
Page: 4 of 5

Solder profile:

JEDEC J-STD-020C



JEDEC

IPC/JEDEC J-STD-020C

July 2004

Supersedes IPC/JEDEC J-STD-020B
July 2002

Table 4-1 SnPb Eutectic Process – Package Peak Reflow Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥ 350
<2.5 mm	240 +0/-5 °C	225 +0/-5 °C
≥ 2.5 mm	225 +0/-5 °C	225 +0/-5 °C

Table 4-2 Pb-free Process – Package Classification Reflow Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 +0 °C *	260 +0 °C *	260 +0 °C *
1.6 mm - 2.5 mm	260 +0 °C *	250 +0 °C *	245 +0 °C *
≥ 2.5 mm	250 +0 °C *	245 +0 °C *	245 +0 °C *

* Tolerances: The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0 °C. For example 260 °C+0 °C) at the rated NSL level.

Table 5-2 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T ₈₀₀ to T _p)	3 °C/second max.	3 °C/second max.
Preheat		
– Temperature Min (T _{preheat})	100 °C	150 °C
– Temperature Max (T _{preheat})	150 °C	200 °C
– Time (t _{preheat} to t _{peak})	60-120 seconds	60-180 seconds
Time maintained above:		
– Temperature (T ₁)	183 °C	217 °C
– Time (t ₁)	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T _p)	See Table 4.1	See Table 4.2
Time within 5 °C of actual Peak Temperature (t _p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	8 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.	8 minutes max.

Note 1: All temperatures refer to top of package, measured on the package body surface.

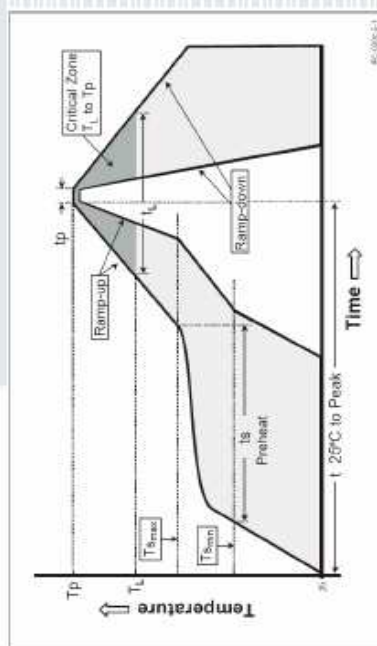


Figure 5-1 Classification Reflow Profile

Your global connection

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Part Number: 1683.09.2610.001

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Signature: Schwaer
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Packaging:

Packaging:

Tape and reel
2000 parts per reel
125 pcs/m
reeldiameter: 330mm

